

Features and Application:

- Enhance the grounding of the cinterion module to the PCB
- Simple production process
 1. SMT process to solder mounting pillars to the PCB
 2. Self-locking screw solution for mounting the module on to the mounting pillars
- Flexible solution with easy access to remove the module

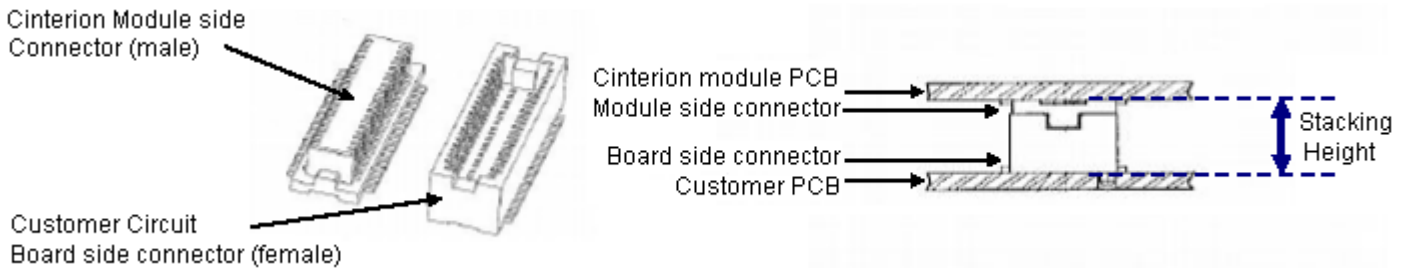
Mounting Pillar and Screw Specifications:

Inner Raw Material	: Ms58 (C3602) copper alloy
First Plating Layer	: Copper flash
Second Plating Layer	: Nickel plating (1 µm)
Third Plating Layer	: Gold plating (0.8 µm)
Weight	: 0.35 g

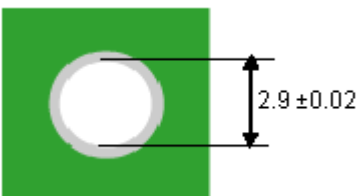
Stacking Height Definition

Dimensions : Millimetres

When both connectors are mated together:



Mounting Instructions



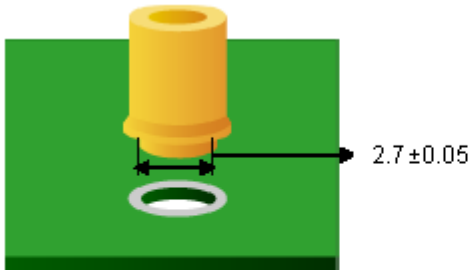
Dimensions : Millimetres

Plated PCB hole size to accommodate the solder mounting pillars
PCB footprint for hole locations

: 2.9 ± 0.02 mm
: Please refer to the cinterion module datasheet

PCB Mounting Pillars

Step1 : SMT Process For Mounting Pillars

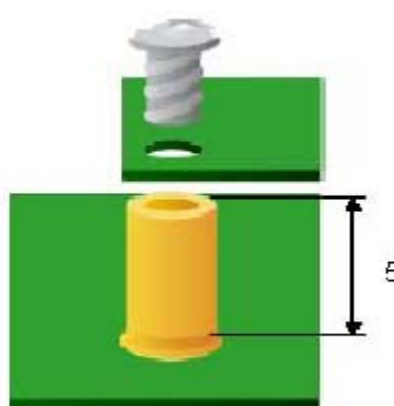
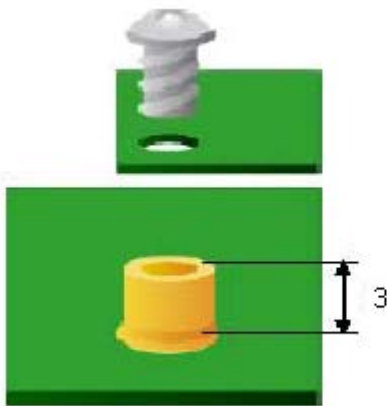


Solder paste applied to pad on PCB



Solder the Mounting Pillar in place using standard surface mount Techniques

Step2 : Mounting the Module with Self-Locking Screws



Dimensions : Millimetres

The torque values for tightening the screws are:

Recommended torque for tightening : 1.5 kgf.cm
 Maximum torque for tightening : 1.7 to 1.8 kgf.cm

Part Number Table

Description	Part Number
Pillar for Cinterion Module, 3 mm	R-14-0076
Pillar for Cinterion Module, 5 mm	R-14-0077

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